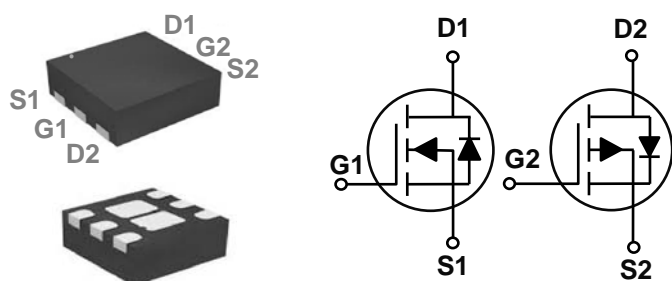


## 20V N+P Dual Channel MOSFETs

### General Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### DFN2X2 Dual 2EP Pin Configuration



BVDSS	RDSON	ID
20V	40mΩ	3.8A
-20V	100mΩ	-2.5A

### Features

- Fast switching
- Green Device Available
- Suit for 1.8V Gate Drive Applications

### Applications

- Notebook
- Load Switch
- Networking
- Hand-held Instruments

### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating		Units
V <sub>DS</sub>	Drain-Source Voltage	20	-20	V
V <sub>GS</sub>	Gate-Source Voltage	±10	±10	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	3.8	-2.5	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	2.3	-1.5	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	15.2	-10	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	1.25	1.25	W
	Power Dissipation – Derate above 25°C	0.01	0.01	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to Ambient	---	100	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	15	°C/W



# FTK2116DFN22

## 20V N+P Dual Channel MOSFETs

N-CH Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$ , $I_D=1mA$	---	0.02	---	V/ $^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=20V, V_{GS}=0V, T_J=25\text{ }^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=16V, V_{GS}=0V, T_J=125\text{ }^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=4.5V, I_D=3A$	---	30	40	m $\Omega$
		$V_{GS}=2.5V, I_D=2A$	---	42	55	m $\Omega$
		$V_{GS}=1.8V, I_D=1.5A$			55	70
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	0.3	0.6	1	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-2	---	mV/ $^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=2A$	---	4.4	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=10V, V_{GS}=4.5V, I_D=3A$	---	5.8	10	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	0.6	1.5	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	1.5	3	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=10V, V_{GS}=4.5V, R_G=25\Omega$ $I_D=1A$	---	2.9	6	ns
$T_r$	Rise Time <sup>2,3</sup>		---	8.4	16	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	19.2	38	
$T_f$	Fall Time <sup>2,3</sup>		---	5.6	12	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, F=1MHz$	---	315	600	pF
$C_{oss}$	Output Capacitance		---	50	80	
$C_{rss}$	Reverse Transfer Capacitance		---	40	60	

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	3.8	A
$I_{SM}$	Pulsed Source Current		---	---	7.6	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25\text{ }^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

## 20V N+P Dual Channel MOSFETs

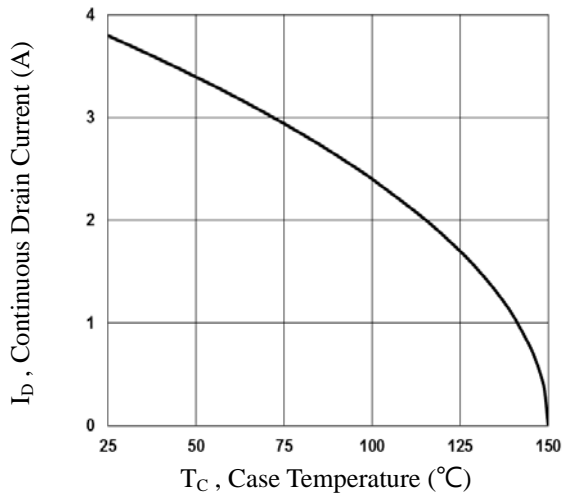


Fig.1 Continuous Drain Current vs.  $T_C$

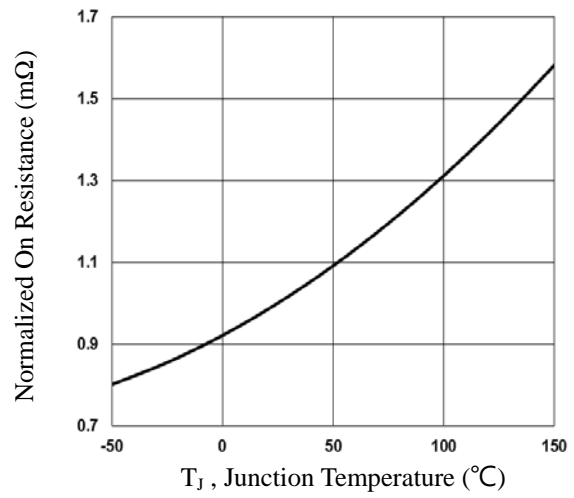


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$

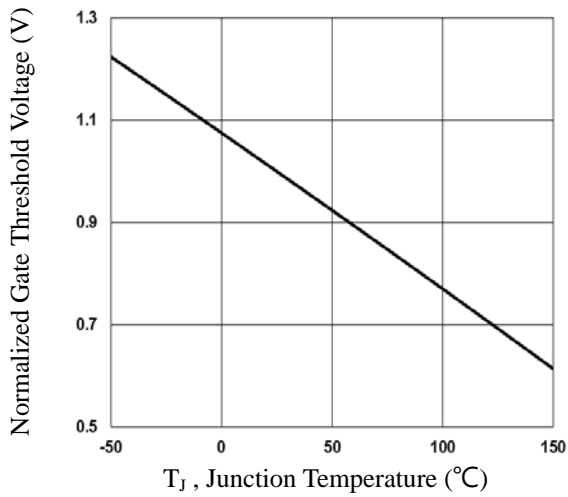


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

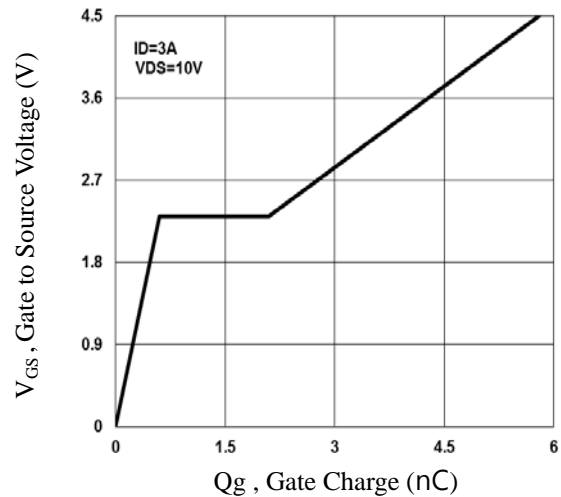


Fig.4 Gate Charge Waveform

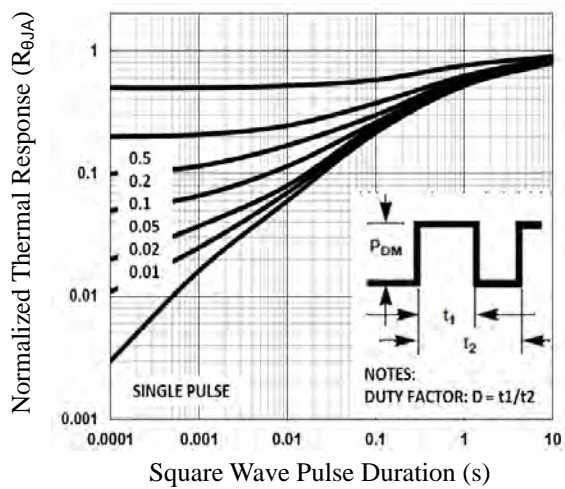


Fig.5 Normalized Transient Impedance

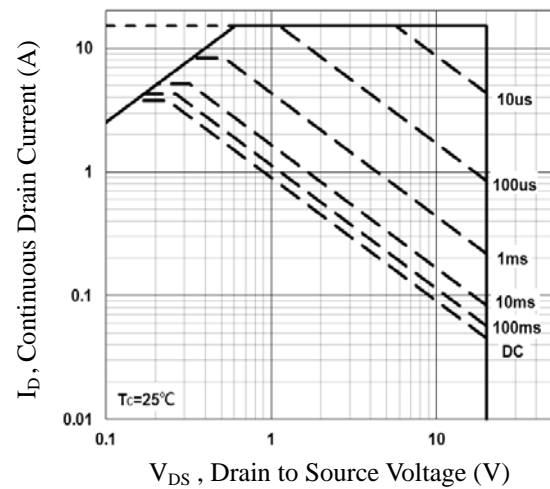


Fig.6 Maximum Safe Operation Area



# FTK2116DFN22

## 20V N+P Dual Channel MOSFETs

P-CH Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.01	---	V/ $^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-20V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	-1	$\mu A$
		$V_{DS}=-16V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	-10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5V, I_D=-3A$	---	82	100	m $\Omega$
		$V_{GS}=-2.5V, I_D=-2A$	---	125	140	m $\Omega$
		$V_{GS}=-1.8V, I_D=-1A$	---	197	230	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.3	-0.6	-1.0	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	3	---	mV/ $^\circ\text{C}$
gfs	Forward Transconductance	$V_{DS}=-10V, I_D=-1A$	---	2.2	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-2A$	---	4.8	10	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	0.5	1	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	1.9	4	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=-10V, V_{GS}=-4.5V, R_G=25\Omega, I_D=-1A$	---	3.5	7	ns
$T_r$	Rise Time <sup>2,3</sup>		---	12.6	24	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	32.6	62	
$T_f$	Fall Time <sup>2,3</sup>		---	8.4	16	
$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, F=1\text{MHz}$	---	350	510	pF
$C_{oss}$	Output Capacitance		---	65	95	
$C_{rss}$	Reverse Transfer Capacitance		---	50	75	

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	-2.5	A
$I_{SM}$	Pulsed Source Current		---	---	-5	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	---	---	-1	V

Note :

4. Repetitive Rating : Pulsed width limited by maximum junction temperature.
5. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
6. Essentially independent of operating temperature.

## 20V N+P Dual Channel MOSFETs

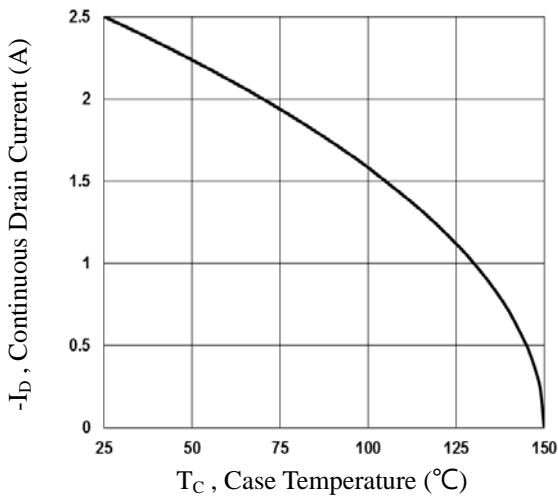


Fig.7 Continuous Drain Current vs.  $T_C$

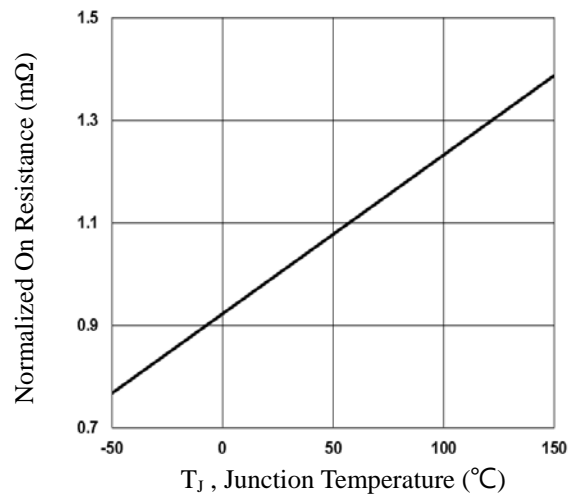


Fig.8 Normalized  $R_{DS(on)}$  vs.  $T_J$

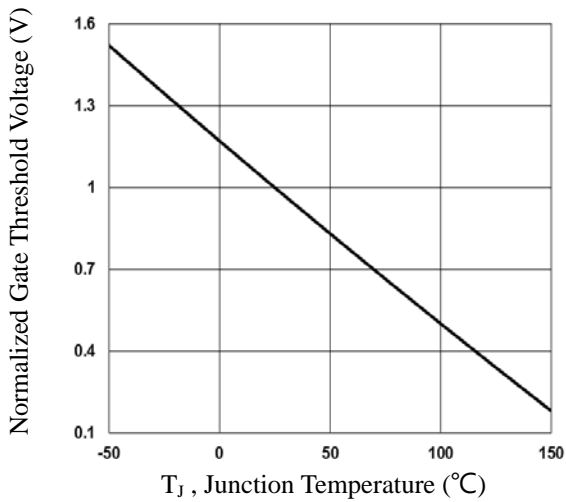


Fig.9 Normalized  $V_{th}$  vs.  $T_J$

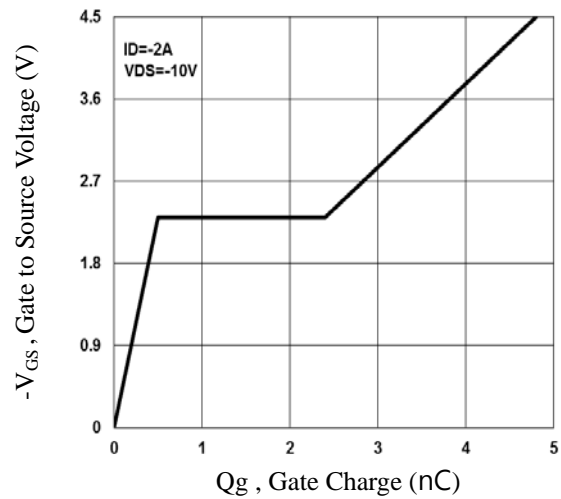


Fig.10 Gate Charge Waveform

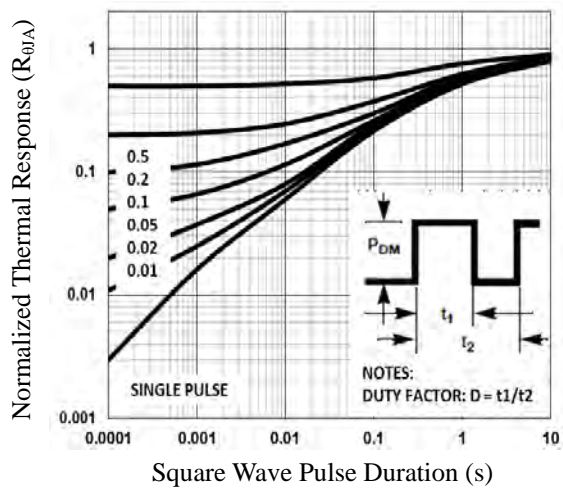


Fig.11 Normalized Transient Impedance

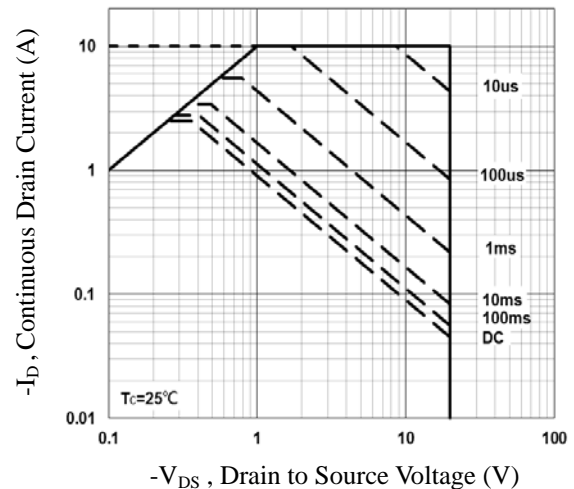
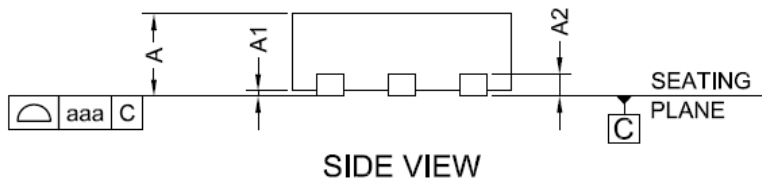
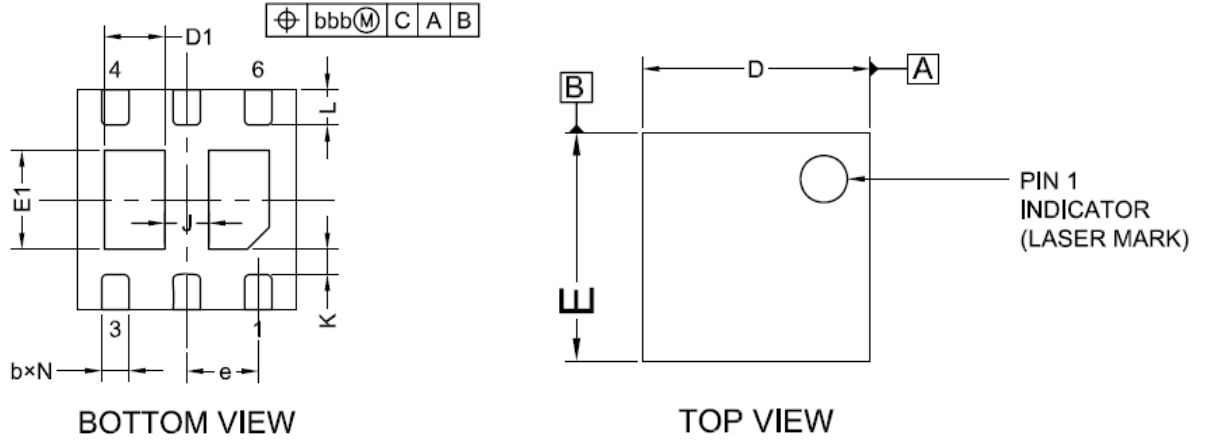


Fig.12 Maximum Safe Operation Area

## 20V N+P Dual Channel MOSFETs

### PPAK2X2 Dual 2EP PACKAGE INFORMATION



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	0,70	0,75	0,80
A1	0,00	0,02	0,05
A2	0,203		
b	0,20	0,25	0,30
D	1,95	2,00	2,05
D1	0,50	0,55	0,60
E	1,95	2,00	2,05
E1	0,85	0,90	0,95
e	0,65BSC		
L	0,27	0,32	0,37
J	0,40BSC		
K	0,20MIN		
N	6		
aaa	0,08		
bbb	0,10		